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November 2009

# FPF1103 / FPF1104 Advance Load Management Switch

#### **Features**

- 1.2V to 4V Input Voltage Operating Range
- Typical R<sub>DS(ON)</sub>:
  - $35m\Omega$  at  $V_{IN}=3.3V$
  - $55m\Omega$  at  $V_{IN}=1.8V$
  - 85mΩ at V<sub>IN</sub>=1.2V
- Slew Rate Control with t<sub>R</sub>: 65µs
- Output Discharge Function on FPF1104
- Low <1µA Quiescent Current at V<sub>ON</sub>=V<sub>IN</sub>
- ESD Protected: Above 4000V HBM, 2000V CDM
- GPIO/CMOS-Compatible Enable Circuitry

## **Applications**

- Mobile Devices and Smart Phones
- Portable Media Devices
- Digital Cameras
- Advanced Notebook, UMPC, MID
- Portable Medical Devices
- GPS and Navigation Equipment

#### Description

The FPF1103/04 are low R<sub>DS</sub> P-channel MOSFET load switches of the IntelliMAX<sup>™</sup> family. Integrated slew-rate control prevents inrush current from glitch supply rails with capacitive loads common in power applications.

The input voltage range operates from 1.2V to 4V to fulfill today's lowest ultra-portable device supply requirements. Switch control is by a logic input (ON-pin) capable of interfacing directly with low-voltage CMOS control signals and GPIOs in embedded processors.

# **Ordering Information**

Part Number	Part Marking	Switch (Typical) At 1.8V <sub>IN</sub>	Input Buffer	Output Discharge	ON Pin Activity	t <sub>R</sub>	Eco Status	Package
FPF1103	Q9	55mΩ	CMOS	NA	Active HIGH	65µs	Green	4-Ball, Wafer-Level Chip-
FPF1104	QA	55mΩ	CMOS	65Ω	Active HIGH	65µs	Green	Scale Package (WLCSP), 1.0 x 1.0mm, 0.5mm Pitch

For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs\_green.html.

# **Application Diagram**

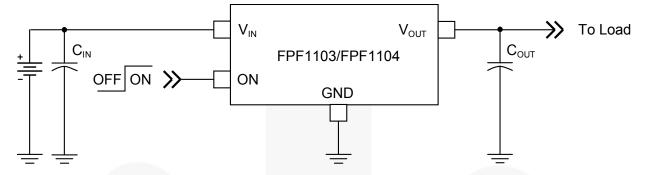


Figure 1. Typical Application

#### Notes:

- 1. C<sub>IN</sub>=1μF, X5R, 0603, for example Murata GRM185R60J105KE26
- 2.  $C_{OUT}$ =1 $\mu$ F, X5R, 0805, for example Murata GRM216R61A105KA01

## **Block Diagram**

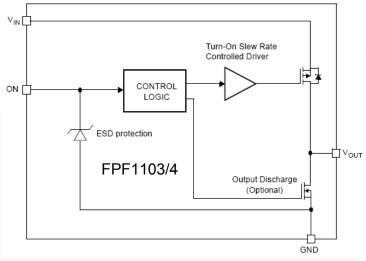


Figure 2. Block Diagram (Output Discharge for FPF1104 Only)

# **Pin Configurations**

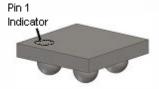


Figure 3. 1 x 1mm WLCSP Bumps Facing Down

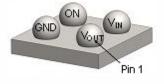


Figure 4. 1 x 1mm WLCSP Bumps Facing Up

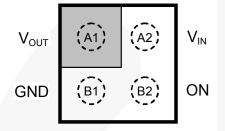


Figure 5. Pin Assignments (Top View)

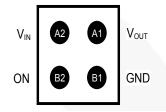


Figure 6. Pin Assignments (Bottom View)

## **Pin Definitions**

Pin#	Name	Description
A1	$V_{OUT}$	Switch Output
A2	$V_{IN}$	Supply Input: Input to the Power Switch
B1	GND	Ground
B2	ON	ON/OFF Control, Active High

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Paramet	Min.	Max.	Unit		
V <sub>IN</sub>	V <sub>IN</sub> , V <sub>OUT</sub> , V <sub>ON</sub> to GND		-0.3	4.2	V	
I <sub>SW</sub>	Maximum Continuous Switch Current			1.2	Α	
P <sub>D</sub>	Power Dissipation at T <sub>A</sub> =25°C			1.0	W	
T <sub>STG</sub>	Storage Junction Temperature			+150	°C	
T <sub>A</sub>	Operating Temperature Range		-40	+85	°C	
0	Thermal Decistones, Junetics to Ambient	1S2P with 1 Thermal Via		95	°C/W	
ΘJA	Thermal Resistance, Junction-to-Ambient	1S2P without Thermal Via		187	C/VV	
ECD	Electrostatic Dischause Comphility	Human Body Model, JESD22-A114	4		137	
ESD	Electrostatic Discharge Capability	Charged Device Model, JESD22-C101	2		kV	

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>IN</sub>	Supply Voltage	1.2	4.0	V
T <sub>A</sub>	Ambient Operating Temperature	-40	+85	°C

### **Electrical Characteristics**

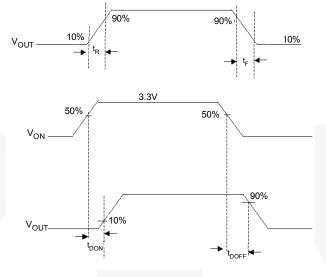
Unless otherwise noted, V<sub>IN</sub>=1.2 to 4.0V, T<sub>A</sub>=-40 to +85°C; typical values are at V<sub>IN</sub>=3.3V and T<sub>A</sub>=25°C.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
Basic Oper	ration						
$V_{IN}$	Supply Voltage		1.2		4.0	V	
I <sub>Q(OFF)</sub>	Off Supply Current	V <sub>ON</sub> =GND, V <sub>OUT</sub> =Open, V <sub>IN</sub> =4V			1	μΑ	
I <sub>SD(OFF)</sub>	Off Switch Current	V <sub>ON</sub> =GND, V <sub>OUT</sub> =GND			1	μA	
-	Ouisseent Current	I <sub>OUT</sub> =0mA, V <sub>ON</sub> =V <sub>IN</sub>			1	μА	
lα	Quiescent Current	I <sub>OUT</sub> =0mA, V <sub>ON</sub> < V <sub>IN</sub>			3		
		V <sub>IN</sub> =3.3V, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C		35	50		
		V <sub>IN</sub> =1.8V, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C		55	70		
$R_{ON}$	On-Resistance	V <sub>IN</sub> =1.5V, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C		70		$m\Omega$	
		V <sub>IN</sub> =1.2V, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C		85	150		
		V <sub>IN</sub> =1.8V, I <sub>OUT</sub> =200mA, T <sub>A</sub> =85°C <sup>(3)</sup>		65	100		
$R_{PD}$	Output Discharge R <sub>PULL DOWN</sub>	V <sub>IN</sub> =3.3V, V <sub>ON</sub> =0V, I <sub>FORCE</sub> =20mA, T <sub>A</sub> =25°C, FPF1104		65	110	Ω	
$V_{IH}$	ON Input Logic High Voltage	V <sub>IN</sub> =1.2V to 4.0V	1.1			V	
V <sub>IL</sub>	ON Input Logic Low Voltage	V <sub>IN</sub> =1.2V to 4.0V			0.35	V	
I <sub>ON</sub> ON Input Leakage		V <sub>ON</sub> =V <sub>IN</sub> or GND	-1		1	μA	
Dynamic C	haracteristics						
t <sub>DON</sub>	Turn-On Delay <sup>(4)</sup>			35		μs	
t <sub>R</sub>	V <sub>OUT</sub> Rise Time <sup>(4)</sup>	$V_{IN}$ =3.3V, $R_L$ =10 $\Omega$ , $C_L$ =0.1 $\mu$ F, $T_A$ =25°C		65		μs	
t <sub>ON</sub>	Turn-On Time <sup>(4,6)</sup>	1 2 3		100		μs	
t <sub>DON</sub>	Turn-On Delay <sup>(4)</sup>			30	50	μs	
t <sub>R</sub>	V <sub>OUT</sub> Rise Time <sup>(4)</sup>	$V_{IN}$ =3.3V, R <sub>L</sub> =500 $\Omega$ , C <sub>L</sub> =0.1 $\mu$ F, T <sub>A</sub> =25°C		40	55	μs	
t <sub>ON</sub>	Turn-On Time <sup>(4,6)</sup>	1A 20 0		70	105	μs	
FPF1103							
t <sub>DOFF</sub>	Turn-Off Delay <sup>(4)</sup>			2.0	2.5	μs	
$t_{F}$	V <sub>OUT</sub> Fall Time <sup>(4)</sup>	V <sub>IN</sub> =3.3V, R <sub>L</sub> =10Ω, C <sub>L</sub> =0.1μF, T <sub>A</sub> =25°C	7	2.2		μs	
toff	Turn-Off <sup>(4,7)</sup>	- TA-23 C		4.2		μs	
t <sub>DOFF</sub>	Turn-Off Delay <sup>(4)</sup>			7.0		μs	
t <sub>F</sub>	V <sub>OUT</sub> Fall Time <sup>(4)</sup>	$V_{IN}$ =3.3V, R <sub>L</sub> =500 $\Omega$ , C <sub>L</sub> =0.1 $\mu$ F, T <sub>A</sub> =25°C		110	У	μs	
t <sub>OFF</sub>	Turn-Off <sup>(4,7)</sup>	14-25 0		117		μs	
FPF1104 <sup>(5)</sup>				)			
t <sub>DOFF</sub>	Turn-Off Delay <sup>(4)</sup>			2.0	2.5	μs	
t <sub>F</sub>	V <sub>OUT</sub> Fall Time <sup>(4)</sup>	$V_{IN}$ =3.3V, $R_L$ =10 $\Omega$ , $C_L$ =0.1 $\mu$ F, $R_{PD}$ =65 $\Omega$ , $T_A$ =25°C		1.9		μs	
t <sub>OFF</sub>	Turn-Off <sup>(4,7)</sup>	1140-0075, 14-50 C		3.9		μs	
t <sub>DOFF</sub>	Turn-Off Delay <sup>(4)</sup>			2.5		μs	
t <sub>F</sub>	V <sub>OUT</sub> Fall Time <sup>(4)</sup>	$V_{IN}$ =3.3V, R <sub>L</sub> =500 $\Omega$ , C <sub>L</sub> =0.1 $\mu$ F, R <sub>PD</sub> =65 $\Omega$ , T <sub>A</sub> =25°C		10.6		μs	
t <sub>OFF</sub>	Turn-Off <sup>(4,7)</sup>	- 117D-0032, 1A-20 C		13.1		μs	

#### Notes:

- 3. This parameter is guaranteed by design and characterization; not production tested.
- 4.  $t_{DON}/t_{DOFF}/t_R/t_F$  are defined in Figure 7.
- 5. Output discharge path is enabled during off.

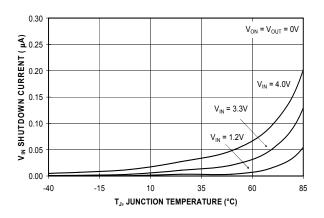
# **Timing Diagram**



#### Notes:

- $t_{\text{ON}} = t_{\text{R}} + t_{\text{DON}}.$   $t_{\text{OFF}} = t_{\text{F}} + t_{\text{DOFF}}.$

Figure 7. Timing Diagram



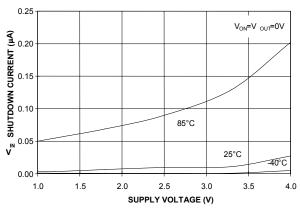
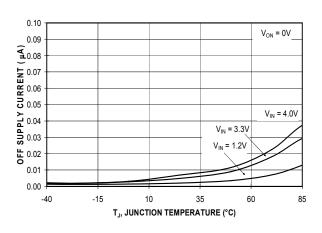


Figure 8. Shutdown Current vs. Temperature





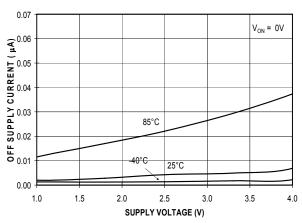
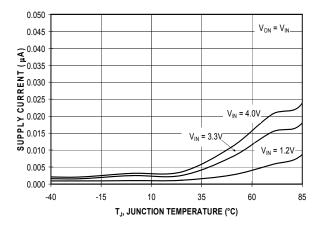


Figure 10.Off Supply Current vs. Temperature (FPF1103, V<sub>OUT</sub> is floating)

Figure 11.Off Supply Current vs. Supply Voltage (FPF1103, V<sub>OUT</sub> is Floating)



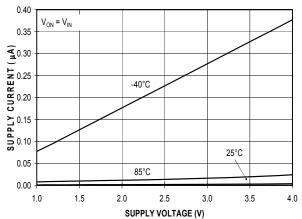
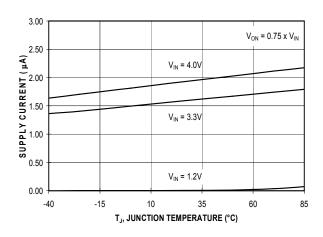


Figure 12. Quiescent Current vs. Temperature  $(V_{ON}=V_{IN})$ 

Figure 13. Quiescent Current vs. Supply Voltage



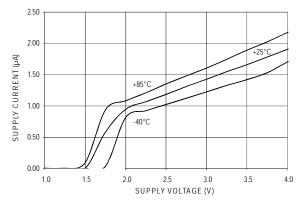


Figure 14. Quiescent Current vs. Temperature  $(V_{ON}$ =0.75 x  $V_{IN})$ 

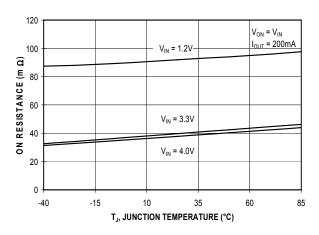


Figure 15. Quiescent Current vs. Supply Voltage at  $V_{ON}$ =1.2V

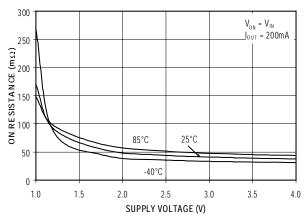


Figure 16.R<sub>ON</sub> vs. Temperature

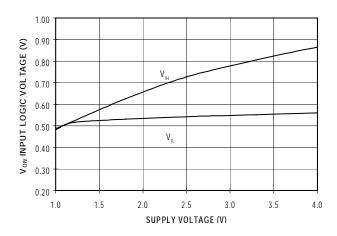
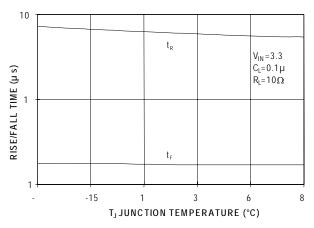


Figure 18.ON-Pin Threshold vs. VIN

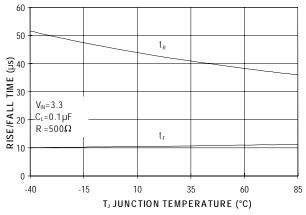
Figure 17.R<sub>ON</sub> vs. Supply Voltage



100  $V_{IN} = 3.3$  $C_{L}=0.1 \mu F$  $t_{DON}$  $R_l = 10\Omega$ ON/OFF DELAY TIME (µs) 10 -15 -40 35 T<sub>J</sub> JUNCTION TEMPERATURE (°C)

Figure 19.V<sub>OUT</sub> Rise and Fall Time vs. Temperature at  $R_L=10\Omega$ 

Temperature at  $R_L$ =10 $\Omega$ 60



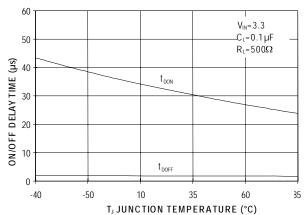


Figure 20.V  $_{\text{OUT}}$  Turn-On and Turn-Off Delay vs.

Figure 21.V<sub>OUT</sub> Rise and Fall Time vs. Temperature at R<sub>L</sub>=500 $\Omega$ 

Figure 22.V<sub>OUT</sub> Turn-On and Turn-Off Delay vs. Temperature at R<sub>L</sub>=500 $\Omega$ 

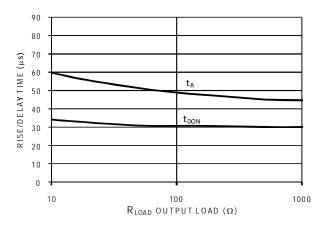
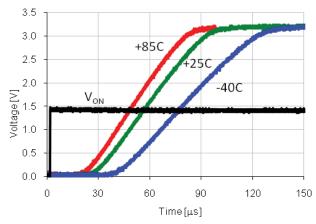


Figure 23.t<sub>R</sub>/t<sub>DON</sub> vs. Output Load at V<sub>IN</sub>=3.3V



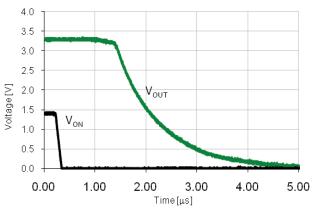


Figure 24.Turn-On Response ( $V_{IN}$ =3.3V,  $C_{IN}$ =1 $\mu$ F,  $C_{OUT}$ =0.1 $\mu$ F,  $R_L$ =10 $\Omega$ )

4.0 3.5 3.0 2.5 2.0 Voltage [V] 1.5 1.0 0.5 0.0 0 30 60 90 120 150 Time[µs]

Figure 26.Turn-On Response  $(V_{IN}=3.3V, C_{IN}=1\mu F, C_{OUT}=0.1\mu F, R_L=500\Omega)$ 

Figure 25.Turn-Off Response (V<sub>IN</sub>=3.3V, C<sub>IN</sub>=1 $\mu$ F, C<sub>OUT</sub>=0.1 $\mu$ F, R<sub>L</sub>=10 $\Omega$ )

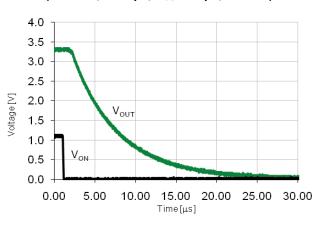


Figure 27.Turn-Off Response  $(V_{IN}=3.3V, C_{IN}=1\mu F, C_{OUT}=0.1\mu F, R_L=500\Omega)$ 

## **Application Information**

#### **Input Capacitor**

An IntelliMAX<sup>TM</sup> switch doesn't require an input capacitor. To reduce device inrush current effect, a  $0.1\mu F$  ceramic capacitor,  $C_{IN}$ , is recommended close to the VIN pin. A higher value of  $C_{IN}$  can be used to further reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

#### **Output Capacitor**

An IntelliMAX<sup>TM</sup> switch works without an output capacitor. However, if parasitic board inductance forces  $V_{\text{OUT}}$  below GND when switching off, a 0.1µF capacitor,  $C_{\text{OUT}}$ , should be placed between  $V_{\text{OUT}}$  and GND.

#### **Fall Time**

Device output fall time can be calculated based on RC constant of the external components as follows:

$$t_{\mathsf{F}} = \mathsf{R}_{\mathsf{L}} \times \mathsf{C}_{\mathsf{L}} \times 2.2 \tag{1}$$

where  $t_{\text{F}}$  is 90% to 10% fall time,  $R_{\text{L}}$  is output load, and  $C_{\text{L}}$  is output capacitor.

The same equation works for a device with a pull-down output resistor.  $R_{\rm L}$  is replaced by a parallel connected pull-down and an external output resistor combination, as follows:

$$t_F = \frac{R_L \times R_{PD}}{R_L + R_{PD}} \times C_L \times 2.2 \tag{2}$$

where  $t_F$  is 90% to 10% fall time,  $R_L$  is output load,  $R_{PD}{=}65\Omega.is$  output pull-down resistor, and  $C_L$  is the output capacitor.

#### **Resistive Output Load**

If resistive output load is missing, the IntelliMAX<sup>TM</sup> switch without a pull-down output resistor is not discharging the output voltage. Output voltage drop depends, in that case, mainly on external device leaks.

## **Recommended Land Pattern and Layout**

For best thermal performance and minimal inductance and parasitic effects, it is recommended to keep input and output traces short and capacitors

as close to the device as possible. Below is a recommended layout for this device to achieve optimum performance.

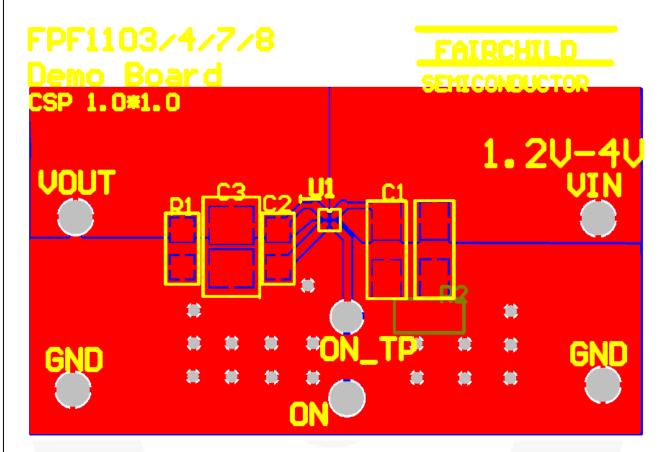
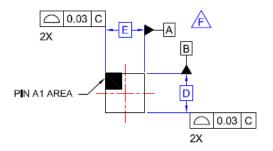
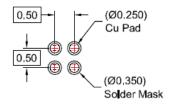


Figure 28.Recommended Land Pattern and Layout

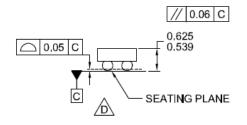
## **Physical Dimensions**



TOP VIEW

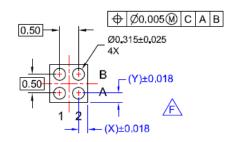


# RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





SIDE VIEWS



**BOTTOM VIEW** 

#### NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14,5M. 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
  - E. PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).

FOR DIMENSIONS D, E, X, AND Y SEE

G. DRAWING FILENAME: MKT-UC004ABrev2.

Figure 29.4 Ball, 1.0 x 1.0mm Wafer-Level Chip-Scale Packaging (WLCSP)

## **Product-Specific Dimensions**

Product	D	E	X	Υ	
FPF1103	960µm ± 30µm	960µm ± 30µm	0.230mm	0.230mm	
FPF1104	960um ± 30µm	960um ± 30µm	0.230mm	0.230mm	

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